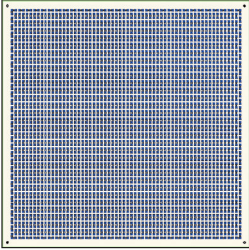
TEG Solution



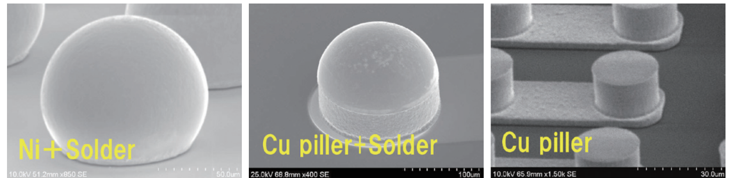
TEG wafer and chips for Assembly technology

1 Custom-make TEG wafer

お客様の仕様に基づくカスタムTEGの作製を承ります。

We make the custom-make wafer, it is based on the specifications of the customer.

- **Wafer size** : φ4inch ～ φ12inch(300mm)
- **Wafer Material** : Si, Glass, GaAs etc.
- **Wire Material** : AL, Au, Cu etc.
- **Layout** : daisy-chain etc.
- **Passivation** : SiO, SiN, PI
- **Bump Material** : Solder bump, Cu pillar, etc.



2 Custom-make Substrate

お客様の仕様に基づくカスタム基板の作製を承ります。

We make the custom-make substrate.

- **Example** : Rigid, Flexible, Glass, etc.

3 Bumping service

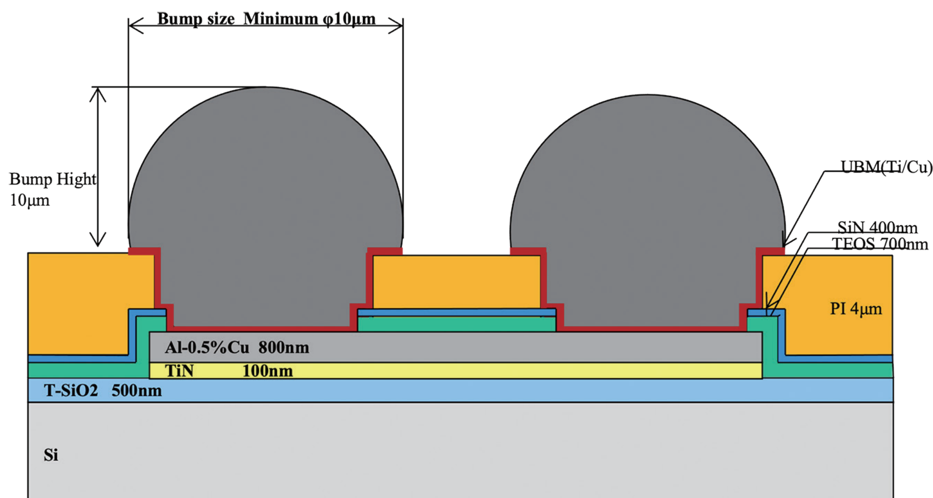
ウエハへのバンプ加工試作を承ります。

We supply the bump processing to the wafer.

4 Wafer thinning & dicing

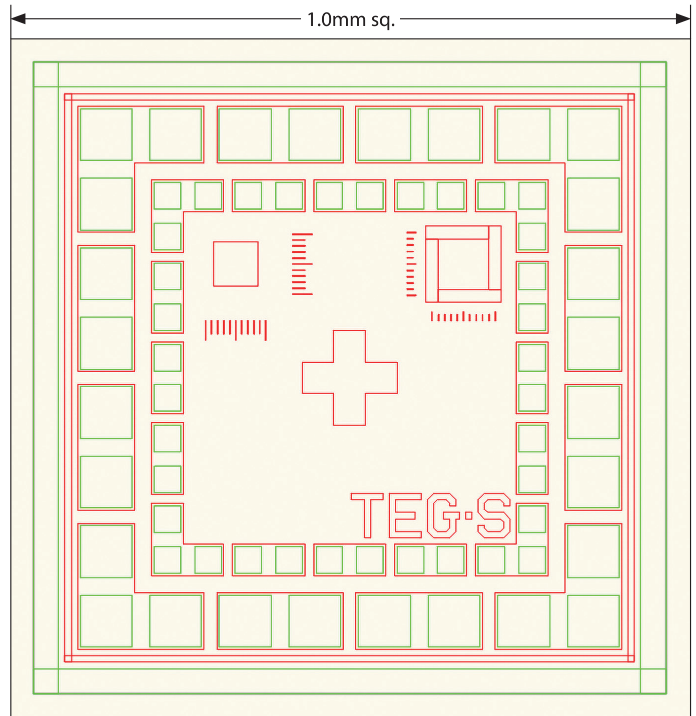
ウエハへの薄加工・ダイシング加工を承ります。

We supply the wafer thinning, dicing.



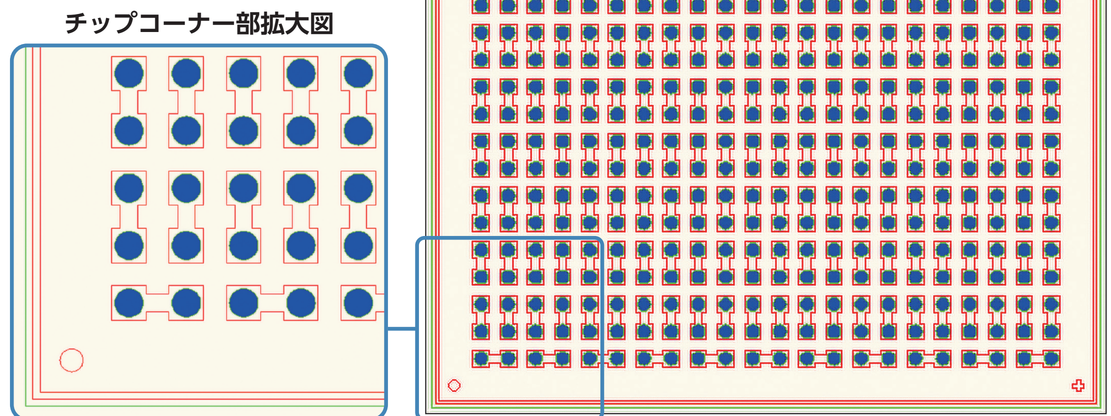
DCC-TEGS01

- **Wafer size** : φ8inch
- **Chip Size** : 1.0mm sq.
- **Pad Metal** : AL-0.5%Cu
- **Pad Pitch** : Out 110um(108pads/chip)
  In 64um
- **Pad Size** : Out 82um sq.
  In 42um sq.



TEG200M_LF

- **Wafer size** : φ8inch
- **Chip Size** : 5.02mm sq.
- **Bump Material** : Sn-3Ag-0.5Cu(SAC305) etc.
- **Bump Pitch** : 200um(22x22=484bumps/chip)
- **Bump Height** : 74um
- **Bump Size** : φ109um
- **Passivation** : PI on SiN



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